

1U MicroChassis built with all aluminum guide decks for rugged applications.

Triple E has a special team dedicated to subsystem design, which typically includes such components as a backplane, a power supply and cooling devices, all completely assembled and fully tested. Triple E is the vendor of choice for companies requiring reliable, rugged systems configured to specification and delivered on time.

The Triple E 1U MicroChassis is constructed using our patented aluminum (901 series) card guide clusters. Designed in accordance with IEEE1101.10 and IEE1101.11 for rear plug up. Accommodates two 6U x 1,6mm x 160mm size boards in front and two 6U x 1,6mm x 80mm direct plug-in rear transition boards. Designed with removable sidewalls for easy maintenance. Cooling is achieved using eight 12VDC 11.00 CFM fans via push-pull method.

Triple E's Microchassis's are built with 0.036" thick zinc plated steel, with a durable black powder coat finish. The power supply is 3U, 300watt PICMG 2.11 compliant. Designed to fit within the 1U rack aperture.

Available with a variety of backplanes including VME64x, CPCI or PICMG 2.16.

Power Supply specifications:

Nominal input: 115 – 240 VAC

Operational input: 90 - 264 VAC

Outputs: +5V/30A, +3.3V/40A, +12V/5A, -12V/1A

Operating Temperature:

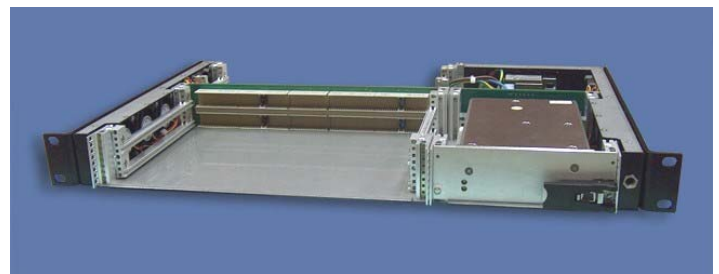
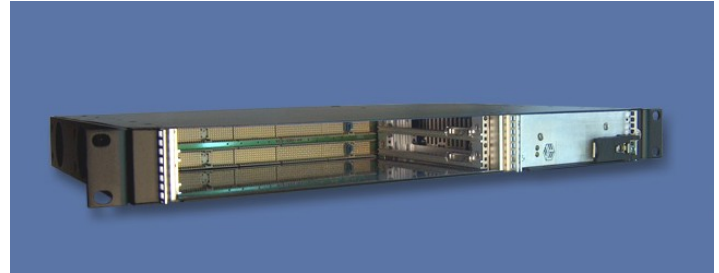
-5° C to +55° C

Storage Temperature:

-40° C to +85° C

Safety Approvals: designed to comply with UL60950, EN60950, UL & CE Marking.

Conducted & Radiated Emission: EN55022 Class B and EN-61000.



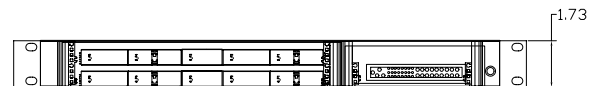
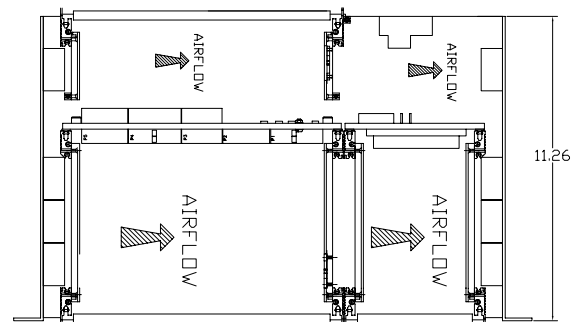
Order Codes:

VME64X with PO/JO Backplane:

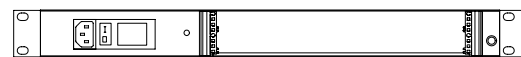
#1U-MXM-6U-02-RM-30-JO-B1

CompactPCI PICMG 2.0 R3.0, Hotswap 2.1 R1.0:

#1U-MCM-6U-84-02-RM-30-AC-B1



FRONT VIEW



REAR VIEW